PRODUCT INTRODUCTION

04 2.5” SATA SSD



Feature

- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm
- Customizable Trigger Pin
- Physical destruction voltage:DC 12V~36V

Specification

Form Factor	2.5 inch	
Connection Type	SATA 7+15pin	
Interface	SATA II	SATA III
Capacity	8GB/16GB/32GB/64GB/128GB	32GB/64GB/128GB/256GB/512GB/1TB/2TB
Max. Sequential Read	240MB/s	520MB/s
Max. Sequential Write	120MB/s	400MB/s
Operating Voltage	5.0V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	100.20x69.85x7.0/9.3mm	

Application



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PRODUCT INTRODUCTION

05 1.8” SATA SSD Products



Feature

- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

Form Factor	1.8 inch	
Connection Type	SATA 7+15pin	
Interface	SATA II	SATA III
Capacity	8GB/16GB/32GB/64GB/128GB	8GB/16GB/32GB/64GB/128GB/256GB/512GB/1TB
Max. Sequential Read	240MB/s	520MB/s
Max. Sequential Write	120MB/s	400MB/s
Operating Voltage	5.0V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	70.00x60.00x7.0mm	

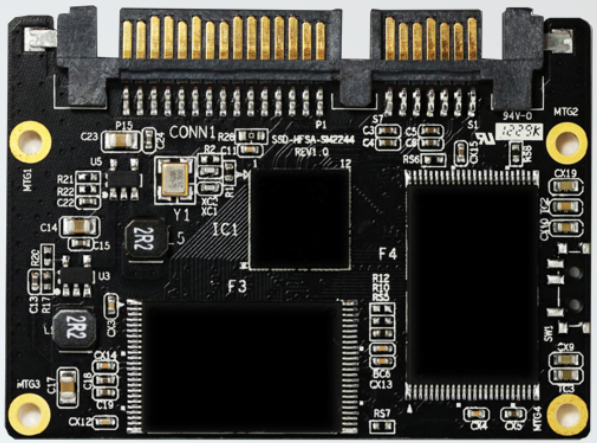
Application



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PRODUCT INTRODUCTION

06 Half Slim SATA SSD



Feature

- Compliant with JEDEC MO-297
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

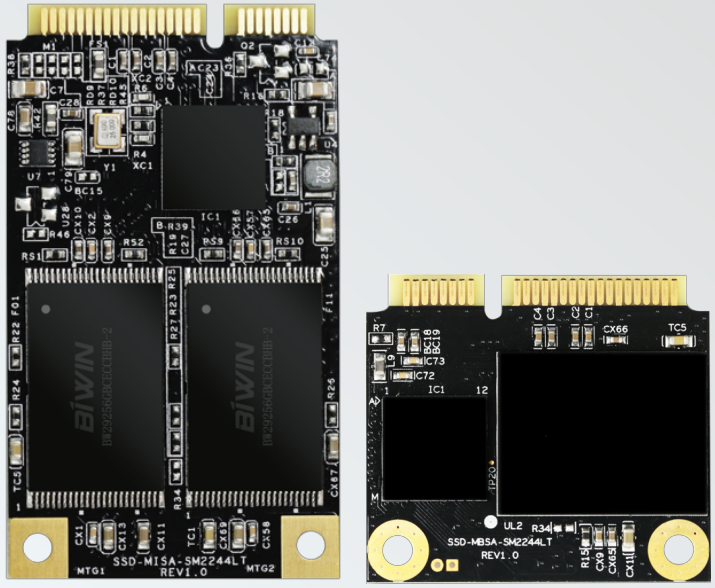
Form Factor	HalfSlim	
Connection Type	SATA 7+15pin	
Interface	SATA II	SATA III
Capacity	8GB/16GB/32GB/64GB	16GB/32GB/64GB/128GB/256GB
Max. Sequential Read	240MB/s	510MB/s
Max. Sequential Write	120MB/s	180MB/s
Operating Voltage	5.0V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	54.0x39.0x4.0mm	

Application

Medical equipment | POS | Industrial tablet | Vehicle terminal | Numerial control machin

PRODUCT INTRODUCTION

07 mSATA Mini mSATA SSD



Feature

- Compliant with JEDEC MO-300
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

Connection Type	mSATA 52pin			
Interface	SATA II		SATA III	
Form Factor	mSATA mini	mSATA	mSATA mini	mSATA
Capacity	16GB~128GB	8GB~256GB	16GB~256GB	32GB~1TB
Max. Sequential Read	240MB/s		520MB/s	
Max. Sequential Write	120MB/s		400MB/s	
Operating Voltage	3.3V +/-5%			
Operating Temperature	-20℃~70℃/-40℃~85℃			
Humidity	0%~95%			
MTBF	2 million hours			
Dimensions	29.85x26.8x3.85mm	50.8x29.85x4.85 mm	29.85x26.8x3.85 mm	50.8x29.85x4.85m m

Application

Medical equipment | POS | Industrial tablet | Vehicle terminal | All-in-one | Advisement player

PRODUCT INTRODUCTION

08 M.2 NGFF SATA SSD



Feature

- Compliant with SATA M.2 SSD standards
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

Form Factor	M.2 2242	M.2 2280
Connection Type		
Interface	SATA III	
Capacity	32GB/64GB/128GB/256GB	32GB/64GB/128GB/256GB/512GB
Max. Sequential Read	510MB/s	510MB/s
Max. Sequential Write	469MB/s	470MB/s
Operating Voltage	3.3V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	42.0x22.0x3.2mm	80.0x22.0x3.2mm

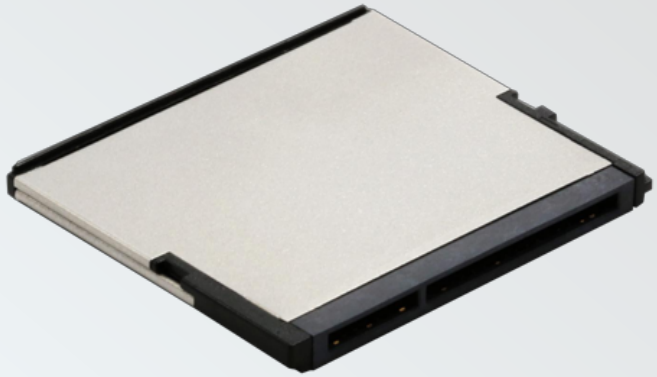
Application

Medical equipment | POS | Industrial tablet | Vehicle terminal | All-in-one | Advisement player

BIWIN®

PRODUCT INTRODUCTION

09 CFast Card



Feature

- Compliant with Cfast specification version 2.0 standards
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

Form Factor	CFast Card	
Connection Type	CFast 7+17pin	
Interface	SATA II	SATA III
Capacity	8GB/16GB/32GB/64GB	32GB/64GB/128GB/256GB/512GB
Max. Sequential Read	228MB/s	510MB/s
Max. Sequential Write	155MB/s	280MB/s
Operating Voltage	3.3V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	42.8x36.4x3.3mm	

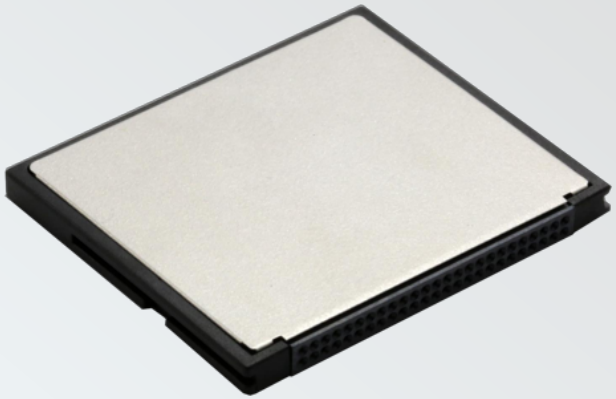
Application



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PRODUCT INTRODUCTION

10 CF Card Products



Feature

- Compliant with CompactFlash specification version 6.0 standards
- Support dynamic power management
- Support wear-leveling algorithm

Specification

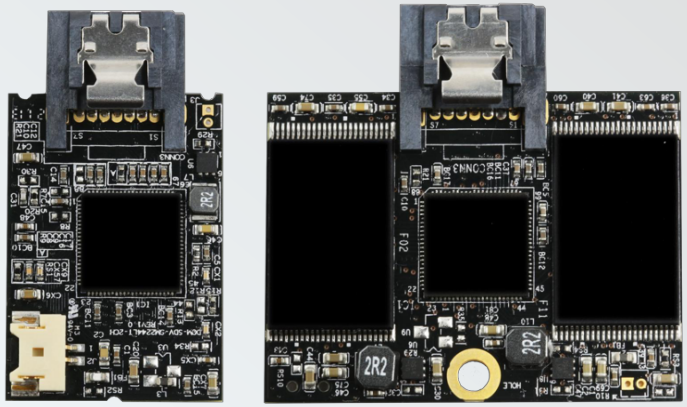
Form Factor	CompactFlash Card
Connection Type	CF 50pin
Interface	PCMCIA/True IDE
Capacity	8GB/16GB/32GB/64GB
Max. Sequential Read	110MB/s
Max. Sequential Write	90MB/s
Operating Voltage	3.3V +/-5%
Operating Temperature	-20℃~70℃/-40℃~85℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	42.8x36.4x3.3mm

Application



PRODUCT INTRODUCTION

11 SATA DOM



Feature

- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm

Specification

Form Factor	SATA DOM
Connection Type	SATA 7pin
Interface	SATA II
Capacity	4GB/8GB/16GB/32GB/64GB
Max. Sequential Read	220MB/s
Max. Sequential Write	90MB/s
Operating Voltage	5.0V +/-5%
Operating Temperature	-20℃~70℃/-40℃~85℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	31.3x22.0x14.0mm(Horizontal); 39.3x22.0x7.1mm(Vertical)

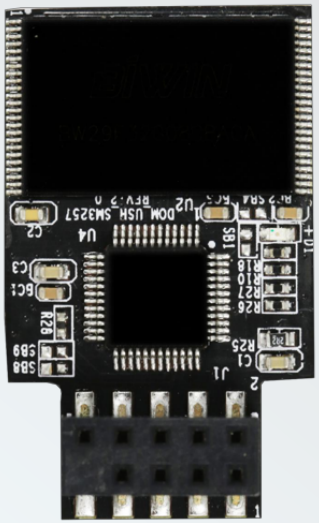
Application

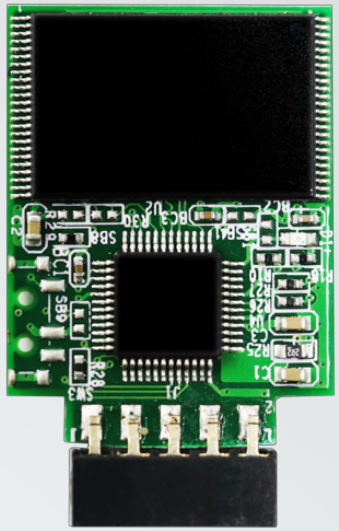


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PRODUCT INTRODUCTION

12 USB DOM





Feature

- Support dynamic power management
- Support global wear-leveling algorithm

Specification

Form Factor	USB DOM
Connection Type	USB 9pin
Interface	USB2.0
Capacity	4GB/8GB/16GB/32GB
Max. Sequential Read	37MB/s
Max. Sequential Write	35MB/s
Operating Voltage	5.0V +/-5%
Operating Temperature	-20℃~70℃/-40℃~85℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	35.0x21.4x6.0mm(Horizontal); 33.8x21.4x5.2mm(Vertical)

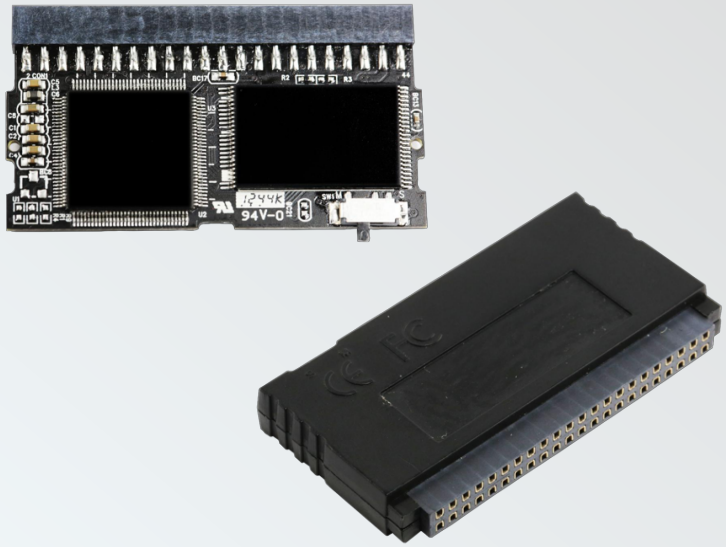
Application



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PRODUCT INTRODUCTION

13 PATA DOM



Feature

- Interface：IDE 40pin or 44pin
- Support dynamic power management
- Support global wear-leveling algorithm
- Master and slave switch(option)

Specification

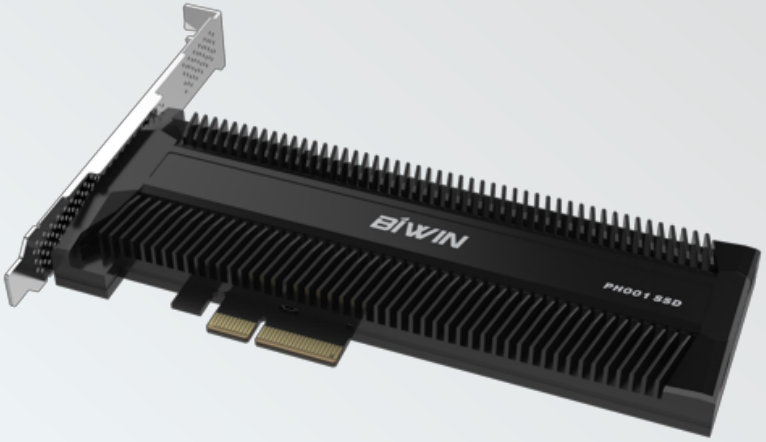
Form Factor	PATA DOM	
Connection Type	IDE40	IDE44
Interface	True IDE	
Capacity	4GB/8GB/16GB/32GB	
Max. Sequential Read	110MB/s	
Max. Sequential Write	50MB/s	
Operating Voltage	5.0V +/-5%	
Operating Temperature	-20℃~70℃/-40℃~85℃	
Humidity	0%~95%	
MTBF	2 million hours	
Dimensions	50.5x23.5x11.5mm	46.8x26.9x6.7mm

Application



PRODUCT INTRODUCTION

14 AIC PCIe SSD



Feature

- 3D NAND+LDPC ECC algorithm
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm
- Support power fail protection
- Support End-to-end data path protection

Specification

Form Factor	Add In Card
Interface	PCIe Gen3x4, NVMe1.3
Capacity	120GB/240GB/480GB/960GB/1.96TB
Max. Sequential Read	3064MB/s
Max. Sequential Write	1763MB/s
Max. Random Read	191K IOPS
Max. Random Write	187K IOPS
Operating Voltage	DC 12.0V +/-5%
Operating Temperature	0~70℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	180.0x115.0x20.0mm

Application



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PRODUCT INTRODUCTION

15

2.5” U.2 SSD



Feature

- 3D NAND+LDPC ECC algorithm
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm
- Support power fail protection
- Support End-to-end data path protection

Specification

Form Factor	SFF-8639 U.2
Interface	PCIe Gen3x4, NVMe1.3
Capacity	120GB/240GB/480GB/960GB/1.96TB
Max. Sequential Read	3064MB/s
Max. Sequential Write	1763MB/s
Max. Random Read	191K IOPS
Max. Random Write	187K IOPS
Operating Voltage	DC 12.0V +/-5%
Operating Temperature	0~70℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	100.00x70.00x9.00mm

Application



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PRODUCT INTRODUCTION

16 Enterprise 2.5” SSD



Feature

- 3D NAND+LDPC ECC algorithm
- Support dynamic power management
- Support Trim、NCQ、SMART
- Support global wear-leveling algorithm
- Support active and passive GC algorithm
- Support power fail protection
- Support End-to-end data path protection

Specification

Form Factor	2.5 inch
Connection Type	SATA 7+15pin
Interface	SATA III
Capacity	120GB/240GB/480GB/960GB/1.96TB
Max. Sequential Read	563MB/s
Max. Sequential Write	510MB/s
Max. Random Read	93K IOPS
Max. Random Write	88K IOPS
Operating Voltage	DC 5.0V +/-5%
Operating Temperature	0~70℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	100.00x70.00x9.00mm

Application



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PRODUCT INTRODUCTION

17 PCIe M.2 SSD



Feature

- 3D NAND+LDPC ECC algorithm;
- Support dynamic power management;
- Support Trim、NCQ、SMART;
- Support global wear-leveling algorithm;
- Support active and passive GC algorithm;
- Support power fail protection;
- Support End-to-end data path protection;

Specification

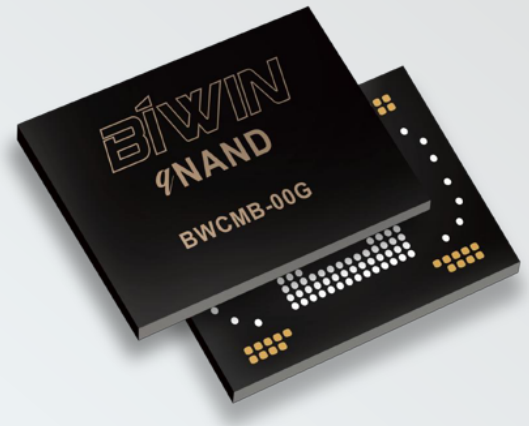
Form Factor	M.2 2280
Interface	PCIe Gen3x4, NVMe1.3
Capacity	128GB/256GB/512GB/1TB
Max. Sequential Read	3064MB/s
Max. Sequential Write	1763MB/s
Max. Random Read	191K
Max. Random Write	187K
Operating Voltage	DC 3.3V +/-5%
Operating Temperature	0~70℃
Humidity	0%~95%
MTBF	2 million hours
Dimensions	80.00x22.00x3.20mm

Application



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18 eMMC



Feature

- BIWIN eMMC is quickly entering the market with its small but advanced design. It uses high-performance control chips and stable NAND flash wafers that improve the efficiency of data transmission, and perform multi-tasking with higher stability and faster speed. BIWIN eMMC has independent intellectual property rights, and features original IDA, Cache Mode, power protection, firmware backup, etc.

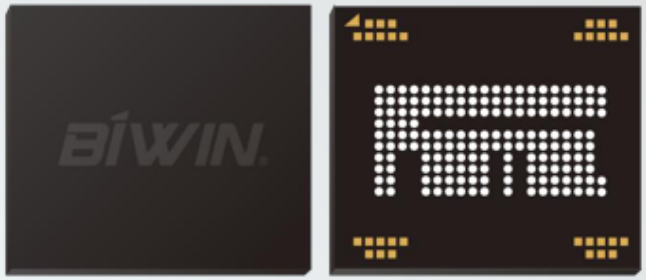
Specification

Interface	eMMC 5.1 & eMMC 4.51
Dimension	LFBGA153: 11.50mm × 13.00mm × 0.90mm 9.00mm × 11.00mm × 0.90mm
	LFBGA169: 12.00mm × 16.00mm × 1.00mm 14.00mm × 18.00mm × 1.00mm
Density	2GB/4GB/8GB/16GB/32GB/64GB/128GB/256GB
Operating voltage	VCC: 2.7V~3.6V; VCCQ: 1.7V~1.95V or 2.7V~3.6V
Operating temperature	Consumer grade: 0℃~70℃ Industrial grade: -40℃~85℃
Packaging	LFBGA153/LFBGA169

Application



19 eMCP



Feature

- eMCP is a superior storage device to eMMC. It packages the eMMC and LPDDR as a whole, not only reducing the volume, but also reducing the circuit design. eMMC in smartphones plays a role similar to the hard disk in a PC, integrating the control and NAND flash in one. Managing flash by an internal controller chip, the CPU does not need to worry about compatibility issues when flash technology is updated.

Specification

Interface	eMMC + LPDDR
Dimension	11.50x13.00mm
Density	8GB+4Gb/8GB+8Gb/16GB+8Gb/16GB+16Gb
Operating voltage	VCC：2.7V~3.6V; VCCQ：1.7V~1.95V or 2.7V~3.6V
eMMC	eMMC 4.51/eMMC 5.0/eMMC 5.1
DRAM	Low Power DDR2/DDR3
Operating temperature	-25° C ~ 85° C
Packaging	FBGA162/FBGA221

Application

Mobile phone Tablet Optical modem

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